36. The microparticle of claim 28, wherein said microparticle has a shape representative of a unique code.

37. The microparticle of claim 28, wherein said microparticle defines pits, holes, or notches that represent a machine readable code.

38. A tagging compound comprising a microparticle that is marked with a machine readable code, wherein said microparticle has a thickness of 0.1μ to 5.0μ, a width of 0.5μ to 50μ, and a length of 0.5μ to 50μ.

39. The tagging compound of claim 38, wherein said microparticle is formed from a wafer.

40. The tagging compound of claim 38, wherein said microparticle comprises silicon, silicon dioxide, or a metal.

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41. The tagging compound of claim 40, wherein said microparticle comprises silicon.

42. The tagging compound of claim 40, wherein said microparticle comprises silicon dioxide.

43. The tagging compound of claim 40, wherein said microparticle comprises aluminum, silver, or gold.

44. The tagging compound of claim 38, wherein said machine readable code is readable by an optical device.

45. The tagging compound of claim 38, wherein said machine readable code comprises data representing more than one bit.

46. The tagging compound of claim 38, wherein said compound is a gas.

47. The tagging compound of claim 38, wherein said compound is a solid.

48. The tagging compound of claim 38, wherein said compound is a liquid.

49. The tagging compound of claim 38, wherein said compound is paint, ink, or fluid dye.

50. The tagging compound of claim 38, wherein said compound is a smoke dye.

51. The tagging compound of claim 38, wherein said microparticle has a shape representative of a unique code.

52. The tagging compound of claim 38, wherein said microparticle defines pits, holes, or notches that represent a machine readable code.

53. A method of marking an object with an invisible code, comprising applying a tagging compound to said object, wherein said tagging compound comprises a microparticle that is marked with a machine readable code and wherein said microparticle has a thickness of 0.1μ to 5.0μ, a width of 0.5μ to 50μ, and a length of 0.5μ to 50μ.

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54. The method of claim 53, wherein said microparticle is formed from a wafer.

55. The method of claim 53, wherein said microparticle comprises silicon, silicon dioxide, or a metal.

56. The method of claim 55, wherein said microparticle comprises silicon.

57. The method of claim 55, wherein said microparticle comprises silicon dioxide.

58. The method of claim 55, wherein said microparticle comprises aluminum, silver, or gold.

59. The method of claim 53, wherein said machine readable code is readable by an optical device.

60. The method of claim 53, wherein said machine readable code comprises data representing more than one bit.

61. The method of claim 53, wherein said compound is a gas.

62. The method of claim 53, wherein said compound is a solid.

63. The method of claim 53, wherein said compound is a liquid.